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## Power Suppply and UA



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ART Circuit	D
Power Management Circuit	
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i can be used to control L80-R's main power on/off. BCKP is supplied, keeping the GPS_EN signal low will make L80-R module enter into backup mode ng the GPS_EN signal to high is the only way to wake the module up. details about power supply circuit, please refer to L80-R Hardware Design.	В
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## L80-R Placement and Design Recommendations

- 1. Keep the module at least 10mm away from the nearest edge of the mother board, that is, it will be better to be placed in the center of the mother board.
- 2. Make ensure the antenna points to the sky.

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- 3. Keep at least 30\*30mm integrated ground around the module (interfering vias is not allowed either).
- 4. Keep the patch antenna at least 10mm away from other tall metal components. Otherwise, the antenna performance will be affected.
- 5. Make sure the microcontroller, crystal, LCD, camera and other high speed components and interfaces are placed on the opposite side of the module, and keep them away from the module as far as possible, such as in diagonal position of the mother board. 6. Make sure interfering signals (USB, LCD, Camera, Crystal, etc.) are in inner layer of the mother board, and keep them and their vias far away from the module. 7. Make sure RF system such as BT/WIFI/GSM is on the opposite side of the module, and keep them away from the module as far as possible, such as in diagonal position of the board.
- 8. Keep DCDC far away from the module.

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- 9. Device enclosure should be made of non-metal materials especially around antenna area. The minimum distance between antenna and enclosure is 1mm.
- 10. The RF part of GPS module is sensitive to temperature, please keep them away from heat-emitting circuit.
- 11. It is recommended to reserve an integrate ground layer to isolate GPS module from others.

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